
Guest editorial

IMAPS 2016 Poland

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the International Society for Hybrid Microelectronics (ISHM)-Poland Chapter, and from the 1997, it became the IMAPS-Poland Chapter.

IMAPS is a non-profit making organization whose aim is to spread knowledge relating to hybrid microelectronics, a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards (PCBs), to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with *IEEE Components, Packaging and Manufacturing Technology* (CPMT) Society, bringing into formation the IMAPS-CPMT organization.

The 40th IMAPS Poland International Conference was held in Wałbrzych in Książ Castle and took place on September 25-28, 2016. This event was organized by the Wrocław University of Science and Technology. The scope of the Conference covered everything in electronics between the chip and the system. The conference was attended by 93 participants, including 16 guests from abroad. During the Conference, 18 invited lectures and 63 posters were presented. The conference was supported by six international journals indexed in Journal Citation Report database and one domestic journal.

This year, as in the previous year, two young Scientists have been awarded, winning the refund of the conference fee of the next IMAPS 2017 Poland Conference.

Also, two awards for women in science have been given by Visegrad International Network for Microelectronics Engineering Scientists.

In the special issue of *Circuit World*, seven papers have been collected, covering the processes and procedures associated with PCB technology. All of them were subjected to the journal's regular reviewing procedure.

The first three papers by Lukacs *et al.*; Arażna *et al.* and Tomaszewski and Potencki describe the investigation of inkjet printing quality on flexible substrates.

Stęplewski *et al.* report about the stability of embedded components in PCB.

The fifth paper by Alafogianni *et al.* proves the influence of varying laser trimming geometries on thin film resistors.

Guzowski *et al.* present the work untitled "RFID monitoring system of fiber optic connectors", and Górecki *et al.* present the paper "Investigations of mutual thermal coupling between SiC Schottky diodes situated in the common case".

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Circuit World*. I hope that it will be of interest to readers of the journal and that it will help them find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about PCBs and related interconnect technologies. I believe that this branch of science could be effectively developed in the future.

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